

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Industrial communication networks – Profiles –
Part 2: Additional fieldbus profiles for real-time networks based on
ISO/IEC/IEEE 8802-3**

**Réseaux de communication industriels – Profils –
Partie 2: Profils de bus de terrain supplémentaires pour les réseaux en temps
réel fondés sur l'ISO/IEC/IEEE 8802-3**



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IEC Central Office
3, rue de Varembe
CH-1211 Geneva 20
Switzerland

Tel.: +41 22 919 02 11
info@iec.ch
www.iec.ch

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